

## LTM4675 - BGA-PBF 108LD 16mm X 11.9mm X 3.51mm (TABLE OF MATERIAL DECLARATION)

The LTM4675 is RoHS compliant per EU RoHS Directive 2003/95/EC.  
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)	
1	Substrate	Circuit Board	0.2297	Barium Compounds	7727-43-7	0.00168	0.73	
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1	0.06407	27.89	
					1156-51-0/9003-36-5/21645-51-2			
					*non-disclosure			
				Copper Metal	7440-50-8	0.10569	46.01	
				Copper Compounds	147-14-8	0.00001	0.01	
				**Ecotoxic substances	7440-38-2	0.00002	0.01	
					7440-28-0			
				Gold metal or alloy	7440-57-5	0.00044	0.19	
				Nickel	7440-02-0	0.00331	1.44	
				Zinc	7440-66-6	0.00021	0.09	
				Continuous Filament Fiber Glass	65997-17-3	0.05038	21.93	
				Acrylic Resin	*non-disclosure	0.00319	1.39	
				Epoxy Resin	*non-disclosure	0.00008	0.04	
				Chromium(III) oxide	1308-38-9	0.00001	0.00	
				Silica amorphous	7631-86-9	0.00012	0.05	
				Talc;not containing fibers like asbestos	14807-96-6	0.00019	0.08	
				Aromatic carbonyl compounds	non-disclosure	0.00018	0.08	
				Cyanoguanidine	461-58-5	0.00000	0.00	
Calcium caobonate	471-34-1	0.00002	0.01					
Amine compounds	*non-disclosure	0.00003	0.01					
Leveling agent and others	*non-disclosure	0.00008	0.03					
2	Solder Paste	Alloy	0.3656	Sn	7440-31-5	0.34736	95.00	
			Sb	7440-36-0	0.01828	5.00		
3	Passive/Active Components		0.3665	Iron Powder (Fe)	7439-89-6	0.26929	73.48	
				Copper (Cu)	7440-50-8	0.07341	20.03	
				Nickel (Ni)	7440-02-0	0.00285	0.78	
				Tin (Sn)	7440-31-5	0.00282	0.77	
				Ceramic (Ba) Compounds	12047-27-7	0.01813	4.95	
4	FC-DFN	-	0.1434	-	-	-	-	
	Chip	Silicon		Silicon	7440-21-3	0.00198	1.38	
	Clip	Copper alloy		Copper	7440-50-8	0.01578	11.01	
				Iron	7439-89-6	0.00039	0.27	
				Zinc	7440-66-6	0.00002	0.02	
	Die & Clip Attach	Epoxy Resin		Lead	7439-92-1	0.00368	2.57	
				Silver	7440-22-4	0.00010	0.07	
				Tin	7440-31-5	0.00020	0.14	
	Encapsulation	Epoxy Resin		Carbon Black	1333-86-4	0.00028	0.20	
				Epoxy Resin	29690-82-2	0.00142	0.99	
				Phenolic resin	9003-35-4	0.00142	0.99	
				Silica, vitreous	60676-86-0	0.02534	17.67	
				Copper	7440-50-8	0.04150	28.94	
	Lead Frame	Copper alloy		Iron	7439-89-6	0.00097	0.68	
				Zinc	7440-66-6	0.00005	0.04	
				Tin	7440-31-5	0.05020	35.01	
	Wire Bond	gold wire		Gold	7440-57-5	0.00005	0.03	
5	Solder Ball	SAC305	0.2421	Sn	7440-31-5	0.23366	96.50	
				Ag	7440-22-4	0.00726	3.00	
				Cu	7440-50-8	0.00121	0.50	
6	Encapsulation	Epoxy Resin	0.3204	Fused Silica	60676-86-0	0.24735	77.20	
				Epoxy Resin	non-disclosure	0.02852	8.90	
				Phenol Resin	non-disclosure	0.02852	8.90	
				Crytalline Silica	14808-60-7	0.00961	3.00	
				Carbon Black	1333-86-4	0.00160	0.50	
				Metal Hydroxide	non-disclosure	0.00481	1.50	
Total Package Weight			1.6678					

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts